Heraeus

File Name: TDS_Conductors_C1075S_(LPA409-021)

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C1075S (LPA409-021)

Conductor

Description

C1075S (LPA409-021) is a screen printable, low cost and oxide-bond pure Ag conductor material. They offer cost savings over standard Ag/Pd formulations, while maintaining the advantages of leach resistance and aged adhesion. C1075S (LPA409-021) is for use on alumina. Resulting films are dense and uniform.

Key Features

- Excellent solderability and leach resistance on alumina
- Compatible with HERAEUS resistors
- Good initial and aged adhesion
- Outstanding conductivity



This picture does not show the packaging of C1075S (LPA409-021) and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Viscosity	30-50 Pas (25 °C, D = 100/s)
Solids	81.5 % ± 1.0 %
Alloy Ratio	100
Coverage	80 cm2/g (FFT: 12 um)
Metal	Ag
Color	Silver

Recommended Processing Guide

Printing Parameters	Print through a 200-325 mesh stainless steel screen. Total thickness: 50-110 um.
Printing Speed	Up to 20 cm/s
Drying Temperature	Dry at 150 °C for 10-20 minutes
Process Temperature (TDS)	Fire at 850 °C (peak) for 10 minutes, and with a total firing cycle time of c. 30-60 minutes.
Film Thickness	13-16 um
Recommended Thinner	HVS 100
Paste Compatibility	Dielectrics: IP9025 Series, IP9029H Resistors:R8900 (WP09-XY) Series

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Warranty

6 months

Storage

Store in a dry and cool condition at 2-23 °C in a dark place with container tightly shut, When stored in a refrigerator, the paste should have acquired room temperature before being opened,

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